Customer Information Notification

202002019I

Issue Date: 14-Feb-2020
Effective Date: 15-Feb-2020

Change Category

☐ Wafer Fab Process
☐ Wafer Fab Materials
☐ Wafer Fab Location
☐ Firmware
☐ Assembly Process
☐ Assembly Materials
☐ Assembly Location
☐ Other
☐ Product Marking
☐ Mechanical Specification
☑ Packing/Shipping/Labeling
☐ Test Location
☐ Test Process
☐ Test Equipment
☐ Design
☐ Errata
☐ Electrical spec./Test coverage

Converting inner packing carton boxes from ATTJ to ATKL

Description

NXP ATTJ is to temporarily use the NXP ATKL inner packing box, which shares the same drawing and manufactured by ATKL box vender, to address the carton box supply shortage.
The temporary solution's period will last around 1 month, starting from Feb 15, 2020

Reason

As the current coronavirus situation in China, the NXP ATTJ packing box's supplier (International paper) could not guarantee on-time delivery. Consequently, NXP ATTJ would like to purchase and use the packing carton box which currently supplies NXP ATKL as a temporary solution to address any packing box supply shortage.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Disposition of Old Products

Only the boxes will be coming from a different supplier. The actual devices are not changing at all.

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Helen Zhu
e-mail address	mailto:helen.zhu@nxp.com?subject=Support

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands